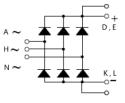




THREE PHASE STANDARD RECOVERY BRIDGE 86A

Features

High Surge Capability Types up to 1600V V_{RRM} Isolation Type Package



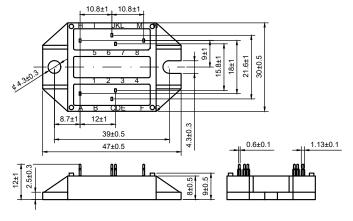


Dimensions in mm (1 mm = 0.0394")

Maximum Ratings

Junction Operating Temperature : -40°C to +150°C Storage Temperature : -40°C to +125°C

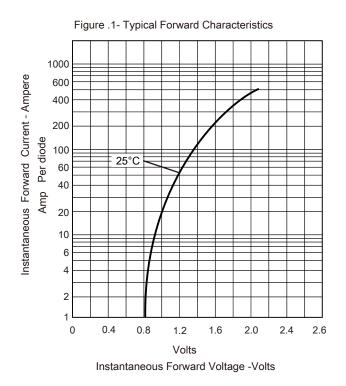
Part Number	Maximum Recurrent Peak Reverse Voltage	Maximum DC Blocking Voltage
DAR3PY086-160W	1600V	1600V

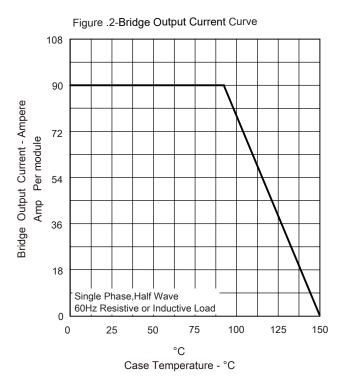


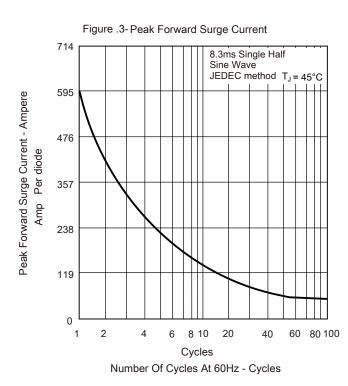
Electrical Characteristics @ 25°C Unless Otherwise Specified

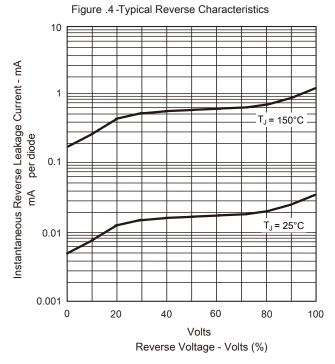
Definition	Conditions		Symbol	min.	typ.	max.	Unit
Bridge output current	Tc = 90°C , per module	T _{VJ} = 150°C	IDAV			90	Α
Max. forward surge current	t = 10 ms; (50 Hz), sine t = 8,3 ms; (60 Hz), sin	$T_{VJ} = 45^{\circ}C$ e $V_R = 0 V$	İFSM			550 595	A A
	t = 10 ms; (50 Hz), sine t = 8,3 ms; (60 Hz), sin	$T_{VJ} = 150^{\circ}C$ e $V_{R} = 0 V$				470 505	A A
Value for fusing	t = 10 ms; (50 Hz), sine t = 8,3 ms; (60 Hz), sine	$T_{VJ} = 45^{\circ}C$ $V_R = 0 V$	· l²t			1.52 1.48	kA²s kA²s
	t = 10 ms; (50 Hz), sine t = 8,3 ms; (60 Hz), sine	$T_{VJ} = 150$ °C $V_R = 0 V$				1.11 1.06	kA²s kA²s
Reverse current	V _R = 1600 V V _R = 1600 V	$T_{VJ} = 25^{\circ}C$ $T_{VJ} = 150^{\circ}C$	I R			40 1.5	μA mA
Forward voltage drop	I _F = 80 A	$T_{VJ} = 25^{\circ}C$	VF			1.5	V
Threshold voltage for power loss calculation only		T _{VJ} = 150°C	V _{F0}			0.8 7.8	V mΩ
Total power dissipation		Tc = 25°C	Ptot			135	W
Junction capacitance	V _R =400 V;f = 1 MHz	T _{VJ} = 25°C	C¹		20		pF
Creepage distance on surface and Striking distance through air		terminal to terminal terminal to backside	d _{Spp/App}	6.0 10.0			mm mm
Isolation voltage	50/60 Hz , RMS; IISOL ≤ 1mA	t = 1 second t = 1 minute	VisoL	3000 2500			V V
Thermal resistance junction to case			R thJC			0.9	K/W
Thermal resistance case to heatsink			R thCH		0.4		K/W
Mounting torque			Мь	1.4		2	Nm













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